

STACKED SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

A stacked semiconductor device has a substrate having a conductor pattern
5 and a die bonding portion. A first die is bonded on the die bonding portion of the
substrate and is electrically connected to the conductor pattern via wires. A first
adhesive layer provided on the substrate to cover the first die and the wires. The first
adhesive layer has a greater top on which a second die is bonded. The second die is
greater than the first die and is electrically connected to the pads of the conductor
10 pattern via wires. A second adhesive layer provided on the substrate to cover the
second die and the wires.